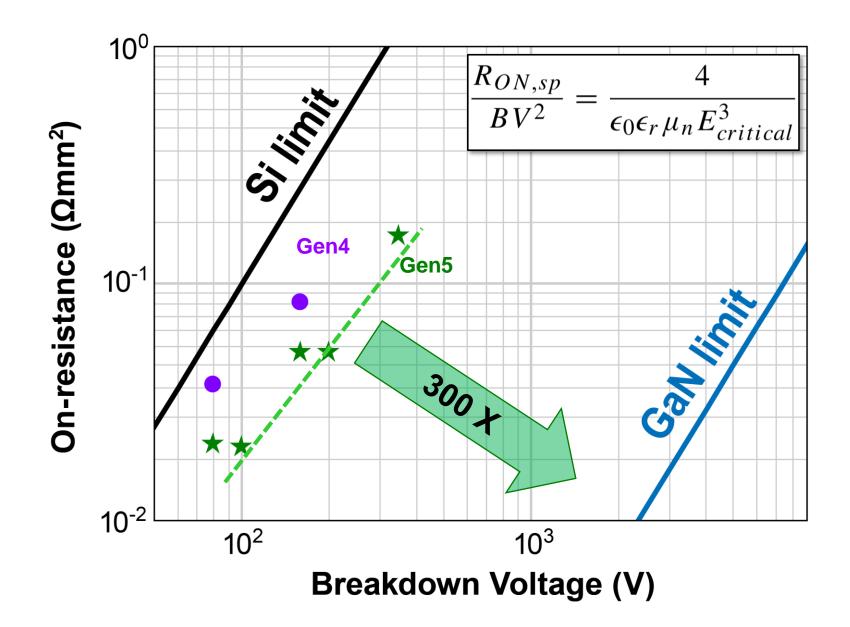


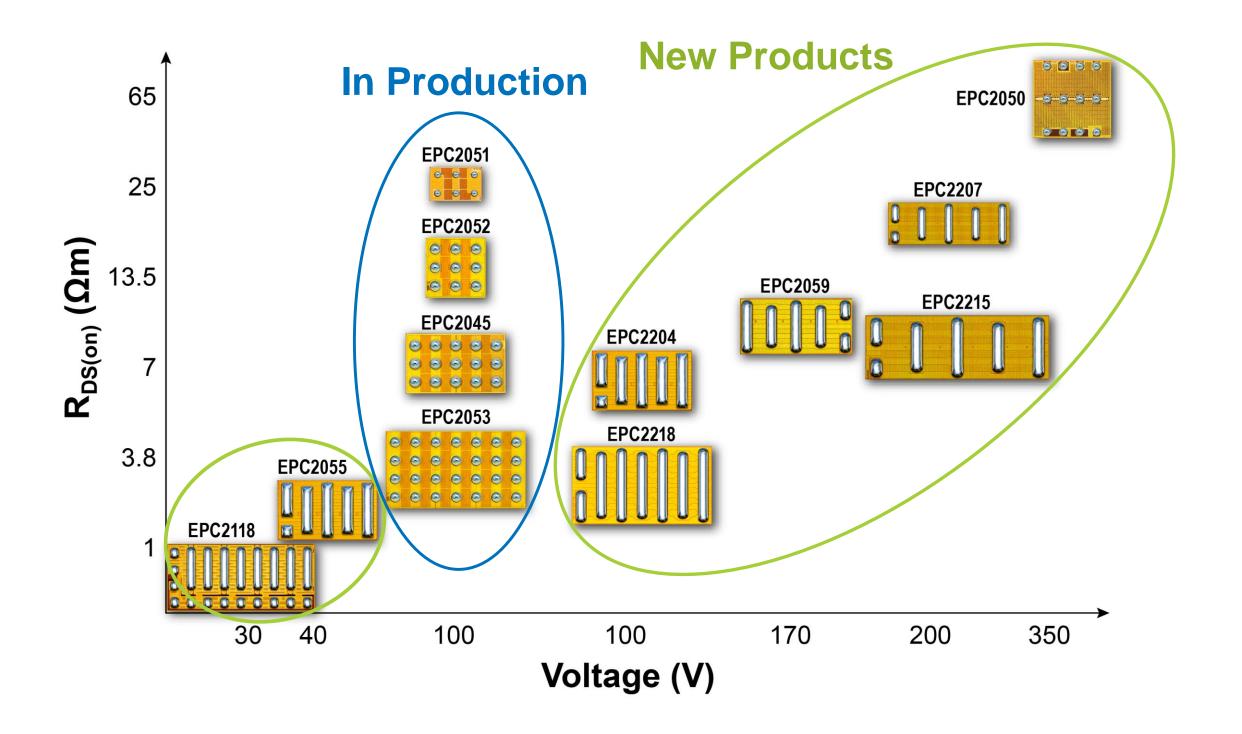
The Path Forward for GaN Power Alex Lidow



eGaN Technology Evolution



Gen5 Product Portfolio



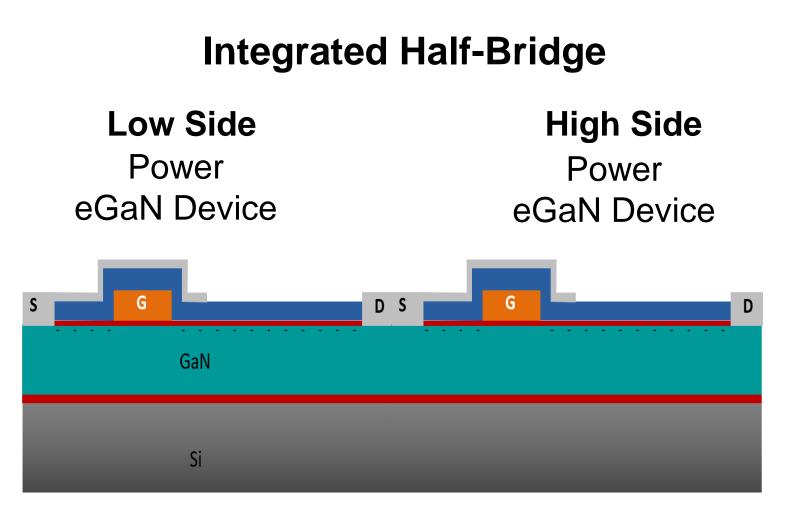
Integrated Circuits





Phase 1: GaN Integration

Being a lateral device, multiple GaN FETs exist side-by-side with **independent** voltage ratings.



Phase 1: Monolithic Half Bridges

30 V – 100 V Symmetric and Asymmetric

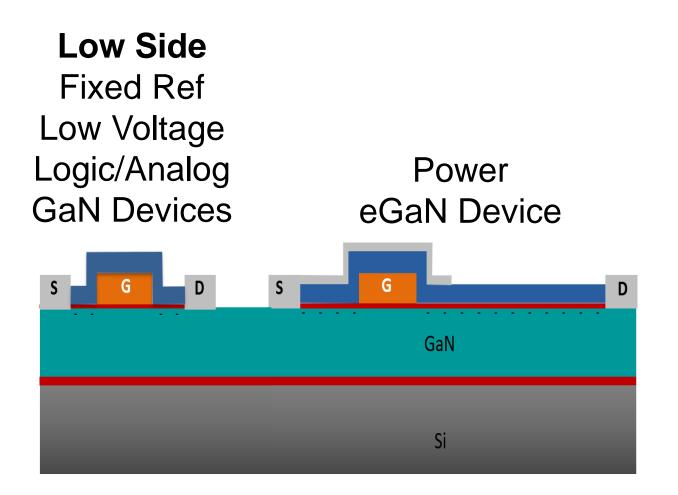
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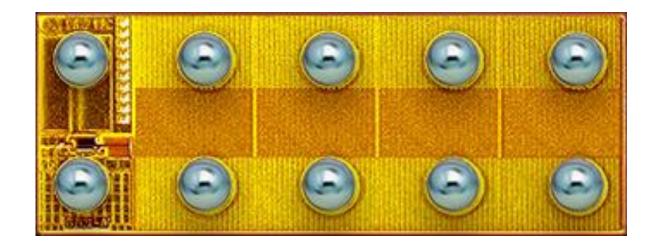
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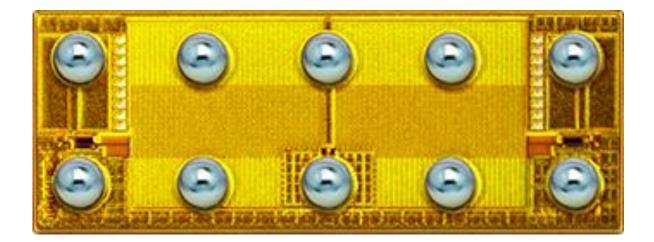
Phase 2: GaN Integration

Being a lateral device, multiple GaN FETs exist side-by-side with **independent** voltage ratings.



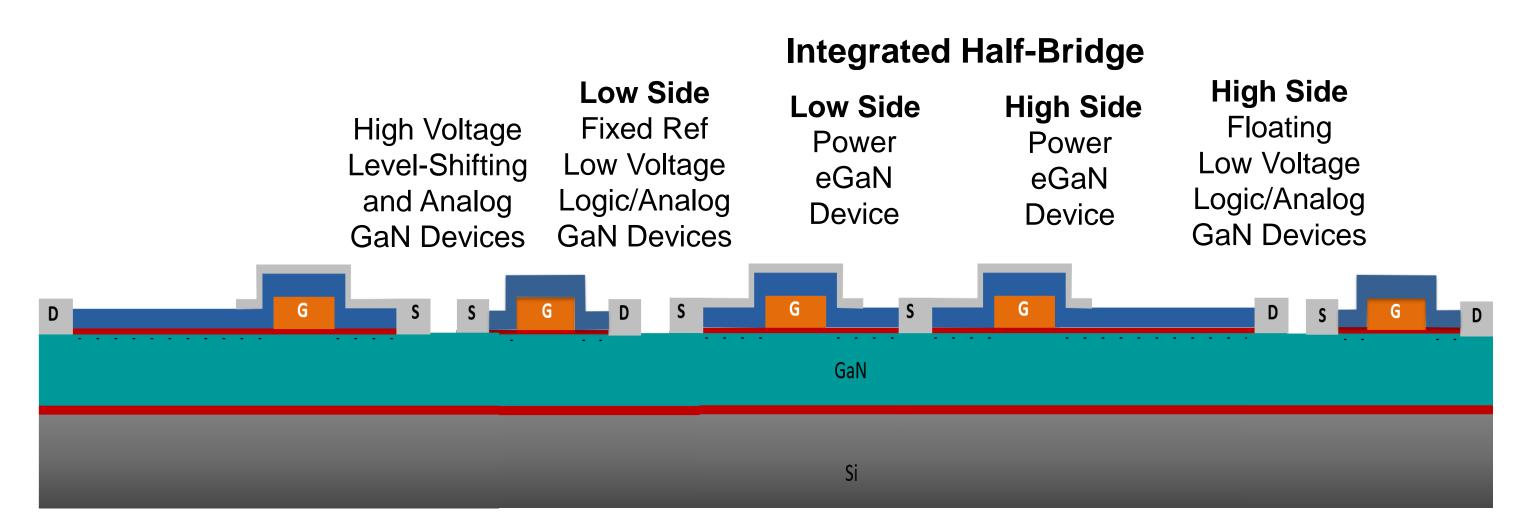
Phase 2: eGaN[®] FET Plus Driver





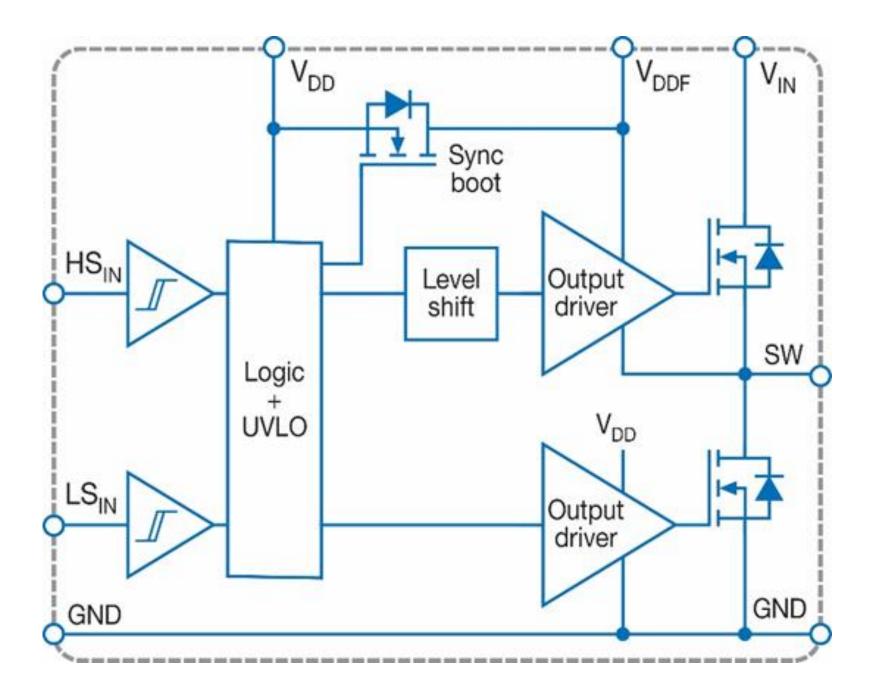
Phase 3: GaN Integration

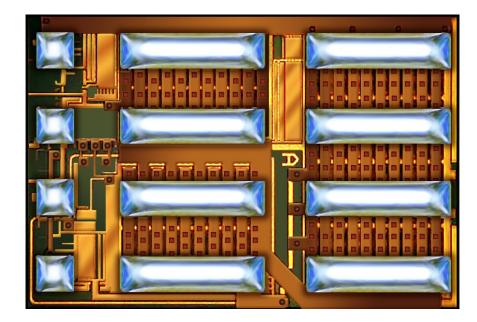
Being a lateral device, multiple GaN FETs exist side-by-side with **independent** voltage ratings.





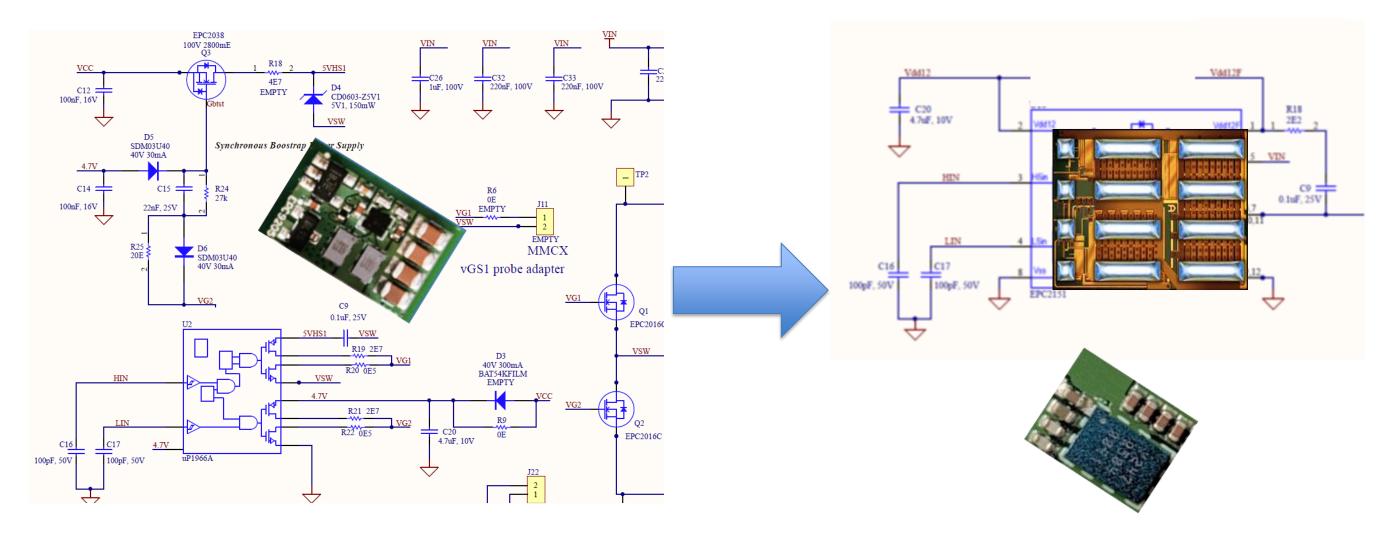
Phase 3: The Integrated Power Stage





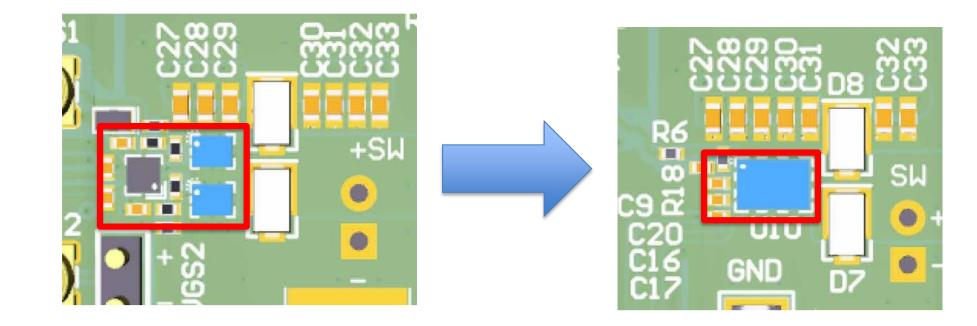


EASY



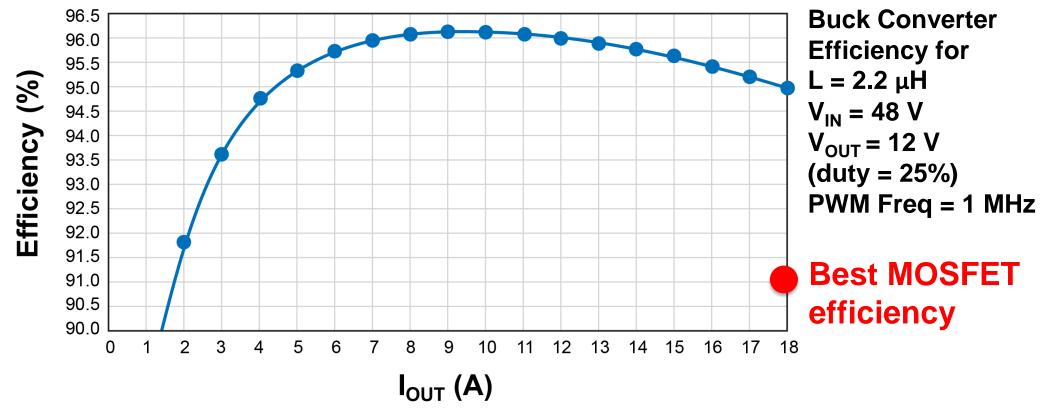
50% Easier to Design LOGIC IN ... POWER OUT

SMALL



33% Smaller in Size on PCB Total number of components = 6 vs.13

EFFICIENT



96% Efficiency for 48 – 12 V Converter

40% Lower Losses than MOSFETs

Summary

- EPC's eGaN technology is developing rapidly
- GaN integrated circuits make products easier to design, smaller, faster, and more efficient
- Discrete devices are becoming obsolete